

December 2015

## **FCP400N80Z**

# N-Channel SuperFET<sup>®</sup> II MOSFET 800 V, 14 A, 400 m $\Omega$

#### **Features**

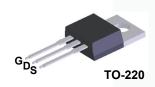
- Typ.  $R_{DS(on)}$  = 340 m $\Omega$
- Ultra Low Gate Charge (Typ. Q<sub>q</sub> = 43 nC)
- Low E<sub>oss</sub> (Typ. 4.1 uJ @ 400 V)
- Low Effective Output Capacitance (Typ.  $C_{oss(eff.)} = 138 pF$ )
- · 100% Avalanche Tested
- · RoHS Compliant
- · ESD Improved Capability

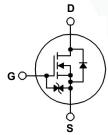
## **Applications**

- AC-DC Power Supply
- · LED Lighting

## Description

SuperFET® II MOSFET is Fairchild Semiconductor's brand-new high voltage super-junction (SJ) MOSFET family that is utilizing charge balance technology for outstanding low on-resistance and lower gate charge performance. This technology is tailored to minimize conduction loss, provide superior switching performance, dv/dt rate and higher avalanche energy. In addition, internal gate-source ESD diode allows to withstand over 2kV HBM surge stress. Consequently, SuperFET II MOSFET is very suitable for the switching power applications such as Audio, Laptop adapter, Lighting, ATX power and industrial power applications.





## Absolute Maximum Ratings T<sub>C</sub> = 25°C unless otherwise noted.

Symbol		Parameter		FCP400N80Z	Unit	
V <sub>DSS</sub>	Drain to Source Voltage			800	V	
V	Gate to Source Voltage	- DC		±20	V	
$V_{GSS}$	GSS Gate to Source voltage	- AC	(f >1 Hz)	±30	v	
. \	Drain Current	- Continuous (T <sub>C</sub> = 25°C)		14	A	
I <sub>D</sub>	Drain Current	- Continuous (T <sub>C</sub> = 100°C)		8.9		
I <sub>DM</sub>	Drain Current	- Pulsed	33	Α		
E <sub>AS</sub>	Single Pulsed Avalanche Energ	Single Pulsed Avalanche Energy (Note 2)		339	mJ	
I <sub>AR</sub>	Avalanche Current	(Note 1)		2.2	Α	
E <sub>AR</sub>	Repetitive Avalanche Energy	ve Avalanche Energy (Note 1)		1.95	mJ	
dv/dt	MOSFET dv/dt			100	V/ns	
αν/αι	Peak Diode Recovery dv/dt		(Note 3)	20	V/IIS	
D	Dower Dissipation	(T <sub>C</sub> = 25°C)		195	W	
P <sub>D</sub> Power Dissipation		- Derate Above 25°C		1.56	W/°C	
T <sub>J</sub> , T <sub>STG</sub>	Operating and Storage Temper	ature Range		-55 to +150	°C	
TL	Maximum Lead Temperature for 1/8" from Case for 5 Seconds	or Soldering,		300	°C	

### **Thermal Characteristics**

Symbol	Parameter FCP400N80Z			
$R_{\theta JC}$	Thermal Resistance, Junction to Case, Max.	0.64	°C/W	
$R_{\theta JA}$	Thermal Resistance, Junction to Ambient, Max.	62.5	- 0/00	

## **Package Marking and Ordering Information**

Part Number	Top Mark	Package	Packing Method	Reel Size	Tape Width	Quantity
FCP400N80Z	FCP400N80Z	TO-220	Tube	N/A	N/A	50 units

## **Electrical Characteristics** $T_C = 25^{\circ}C$ unless otherwise noted.

Symbol	Parameter	Test Conditions	Min.	Тур.	Max.	Unit
Off Charac	cteristics					
BV <sub>DSS</sub>	Drain to Source Breakdown Voltage	$V_{GS} = 0 \text{ V}, I_D = 1 \text{ mA}, T_J = 25^{\circ}\text{C}$	800	-	-	V
ΔBV <sub>DSS</sub> / ΔT <sub>J</sub>	Breakdown Voltage Temperature Coefficient	I <sub>D</sub> = 1 mA, Referenced to 25°C	-	0.8	-	V/°C
1	Zero Gate Voltage Drain Current	V <sub>DS</sub> = 800 V, V <sub>GS</sub> = 0 V	-	-	25	μА
I <sub>DSS</sub>	Zelo Gate Voltage Diam Guilent	$V_{DS} = 640 \text{ V}, T_{C} = 125^{\circ}\text{C}$	-	-	250	μΑ
$I_{GSS}$	Gate to Body Leakage Current	$V_{GS} = \pm 20 \text{ V}, V_{DS} = 0 \text{ V}$	-	-	±10	μΑ

#### **On Characteristics**

V <sub>GS(th)</sub>	Gate Threshold Voltage	$V_{GS} = V_{DS}$ , $I_D = 1.1 \text{ mA}$	2.5	-	4.5	V
R <sub>DS(on)</sub>	Static Drain to Source On Resistance	$V_{GS} = 10 \text{ V}, I_D = 5.5 \text{ A}$	-	0.34	0.4	Ω
9 <sub>FS</sub>	Forward Transconductance	$V_{DS} = 20 \text{ V}, I_{D} = 5.5 \text{ A}$	-	12	-	S

## **Dynamic Characteristics**

C <sub>iss</sub>	Input Capacitance	100 1/ 100	-	1770	2350	pF
C <sub>oss</sub>	Output Capacitance	V <sub>DS</sub> = 100 V, V <sub>GS</sub> = 0 V, f = 1 MHz		51	70	pF
C <sub>rss</sub>	Reverse Transfer Capacitance			0.5	-	pF
C <sub>oss</sub>	Output Capacitance	$V_{DS} = 480 \text{ V}, V_{GS} = 0 \text{ V}, f = 1 \text{ MHz}$	- \	28	-	pF
C <sub>oss(eff.)</sub>	Effective Output Capacitance	V <sub>DS</sub> = 0 V to 480 V, V <sub>GS</sub> = 0 V		138	-	pF
Q <sub>g(tot)</sub>	Total Gate Charge at 10V	V <sub>DS</sub> = 640 V, I <sub>D</sub> = 11 A,	-	43	56	nC
$Q_{gs}$	Gate to Source Gate Charge	V <sub>GS</sub> = 10 V	-	8.6	-	nC
$Q_{gd}$	Gate to Drain "Miller" Charge	(Note 4)	-	17	-	nC
ESR	Equivalent Series Resistance	f = 1 MHz	-	2.3	-	Ω

## **Switching Characteristics**

t <sub>d(on)</sub>	Turn-On Delay Time		- /	20	50	ns
t <sub>r</sub>		$V_{DD} = 400 \text{ V}, I_{D} = 11 \text{ A},$	- /	12	34	ns
t <sub>d(off)</sub>	Turn-Off Delay Time	$V_{GS} = 10 \text{ V}, R_g = 4.7 \Omega$	-	51	112	ns
t <sub>f</sub>	Turn-Off Fall Time	(Note 4)	/-	2.6	15	ns

#### **Drain-Source Diode Characteristics**

Is	Maximum Continuous Drain to Source Dioc	Maximum Continuous Drain to Source Diode Forward Current			14	Α
I <sub>SM</sub>	Maximum Pulsed Drain to Source Diode Forward Current			-	33	Α
$V_{SD}$	Drain to Source Diode Forward Voltage V <sub>GS</sub> = 0 V, I <sub>SD</sub> = 11 A		-	- //	1.2	V
t <sub>rr</sub>	Reverse Recovery Time	V <sub>GS</sub> = 0 V, I <sub>SD</sub> = 11 A,	-	395	-	ns
Q <sub>rr</sub>	Reverse Recovery Charge dl <sub>F</sub> /dt = 100 A/μs		-	7.4	-	μС

#### Notes:

- ${\it 1. Repetitive\ rating: pulse-width\ limited\ by\ maximum\ junction\ temperature.}$
- 2. I $_{AS}$  = 2.2 A, V $_{DD}$  = 50 V, R $_{G}$  = 25  $\Omega$ , starting T $_{J}$  = 25°C.
- 3. I  $_{SD} \leq$  14 A, di/dt  $\leq$  200 A/µs, V  $_{DD} \leq$  BV  $_{DSS},$  starting T  $_{J}$  = 25°C.
- 4. Essentially independent of operating temperature typical characteristics.

## **Typical Performance Characteristics**

Figure 1. On-Region Characteristics

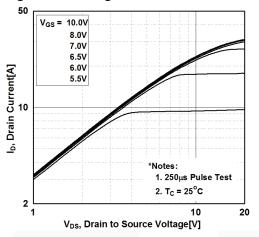


Figure 3. On-Resistance Variation vs.

Drain Current and Gate Voltage

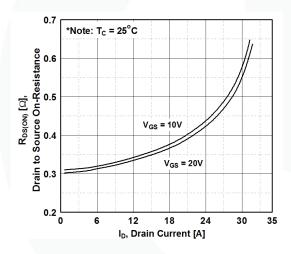


Figure 5. Capacitance Characteristics

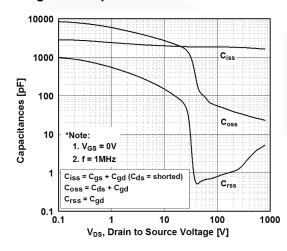


Figure 2. Transfer Characteristics

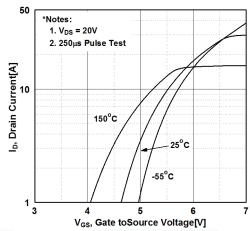


Figure 4. Body Diode Forward Voltage Variation vs. Source Current and Temperature

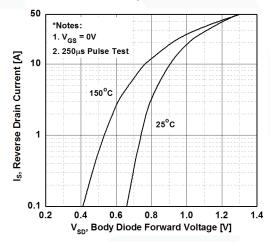
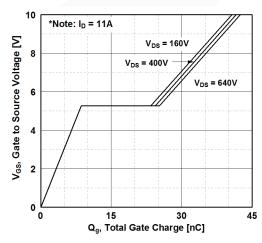


Figure 6. Gate Charge Characteristics



## **Typical Performance Characteristics** (Continued)

Figure 7. Breakdown Voltage Variation vs. Temperature

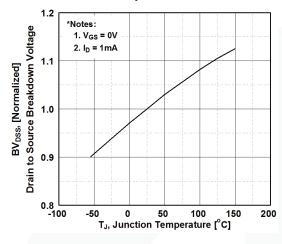


Figure 9. Maximum Safe Operating Area

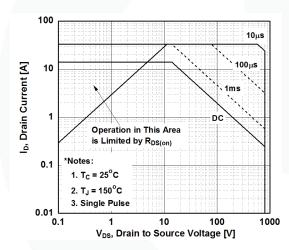


Figure 11. Eoss vs. Drain to Source Voltage

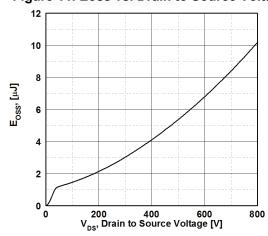


Figure 8. On-Resistance Variation vs. Temperature

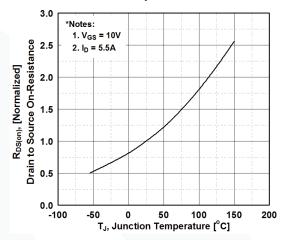
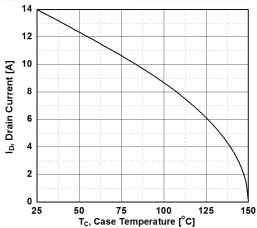
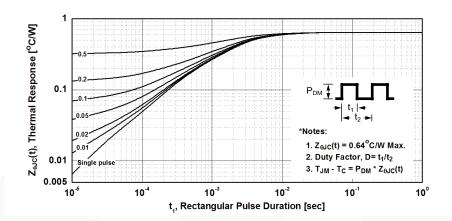


Figure 10. Maximum Drain Current vs. Case Temperature



## **Typical Performance Characteristics** (Continued)

Figure 12. Transient Thermal Response Curve



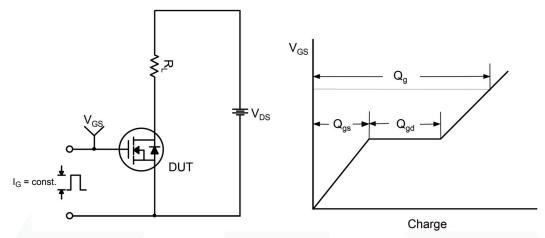


Figure 13. Gate Charge Test Circuit & Waveform

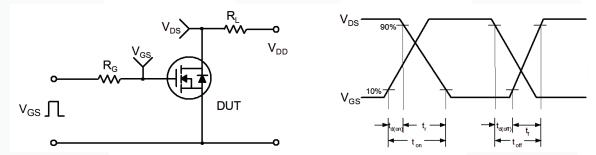


Figure 14. Resistive Switching Test Circuit & Waveforms

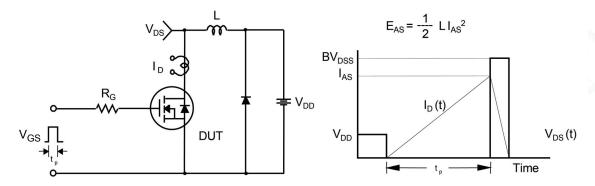


Figure 15. Unclamped Inductive Switching Test Circuit & Waveforms

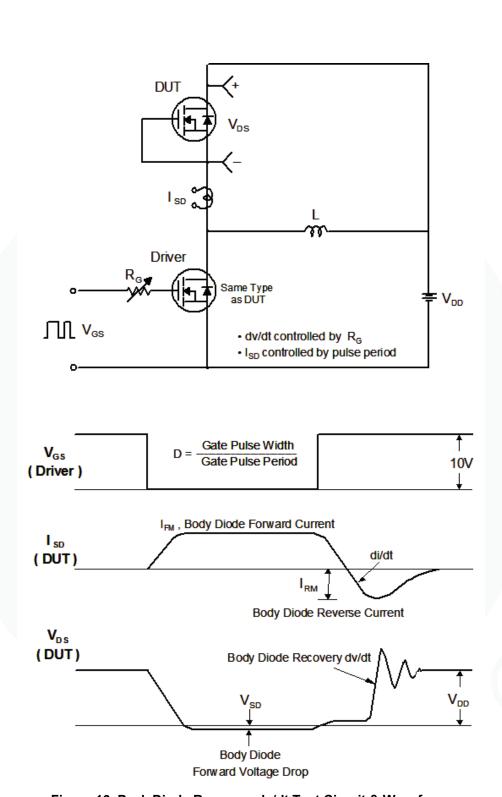


Figure 16. Peak Diode Recovery dv/dt Test Circuit & Waveforms







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